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United States Patent [19]
Matsushima

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[54] **INNER TUBE FOR USE IN A SEMICONDUCTOR WAFER HEAT PROCESSING APPARATUS**

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[**] Term: **14 Years**

[21] Appl. No.: **74,301**

[22] Filed: **Jul. 24, 1997**

[30] **Foreign Application Priority Data**

Jan. 31, 1997 [JP] Japan 9-2653

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; D15/144,
D15/144.1, 199; 414/935-941, 217, 147;
437/247, 546; D23/259, 262, 266

[56] **References Cited**

U.S. PATENT DOCUMENTS

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[57] **CLAIM**

I claim the ornamental design for inner tube for use in a semiconductor wafer heat processing apparatus, as shown and described.

DESCRIPTION

FIG. 1: a perspective view of a inner tube for use in a semiconductor wafer heat processing apparatus;

FIG. 2: a front elevational view thereof, the rear elevational view, the right side view and the left side view are identical with the front view;

FIG. 3: a top plan view thereof;

FIG. 4: a bottom plan view thereof; and,

FIG. 5: a cross sectional view thereof taken along line V-V in FIG. 3.

1 Claim, 2 Drawing Sheets

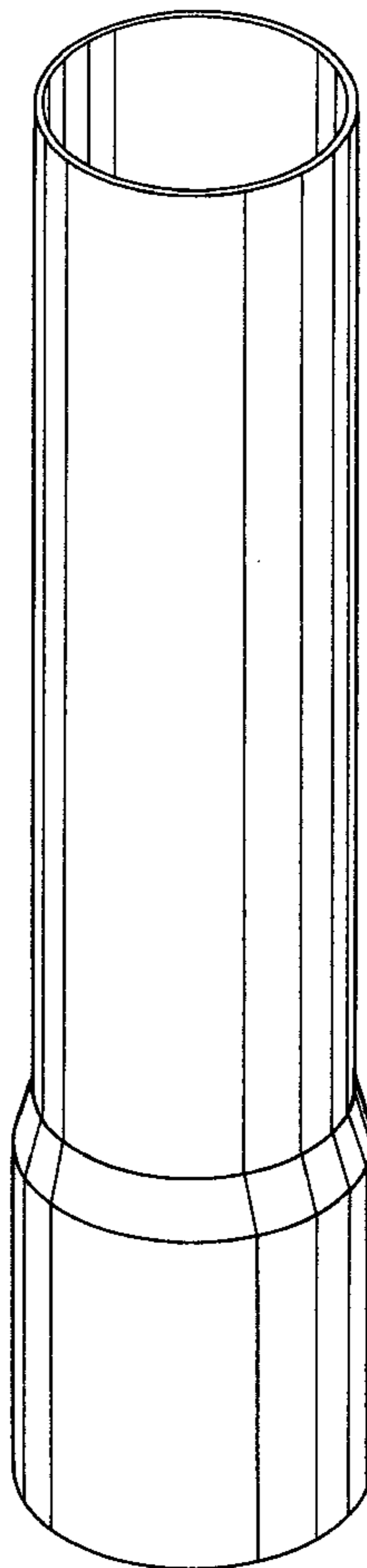


FIG. 1

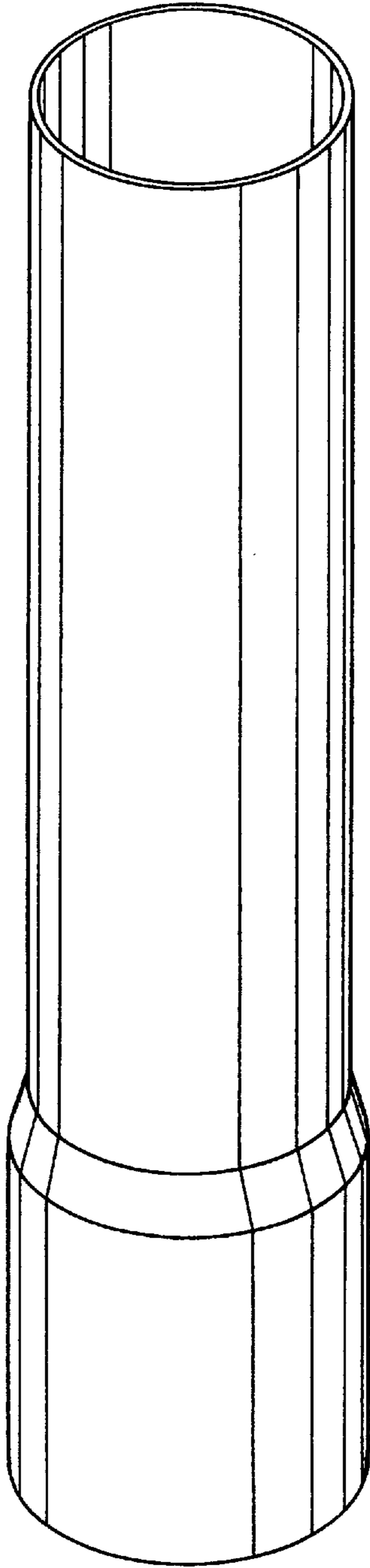


FIG. 2

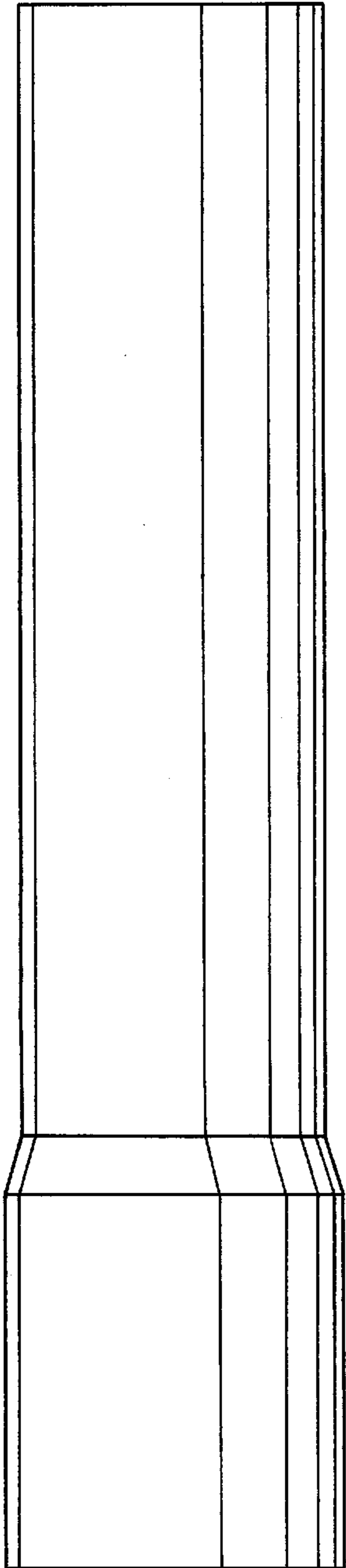


FIG. 3

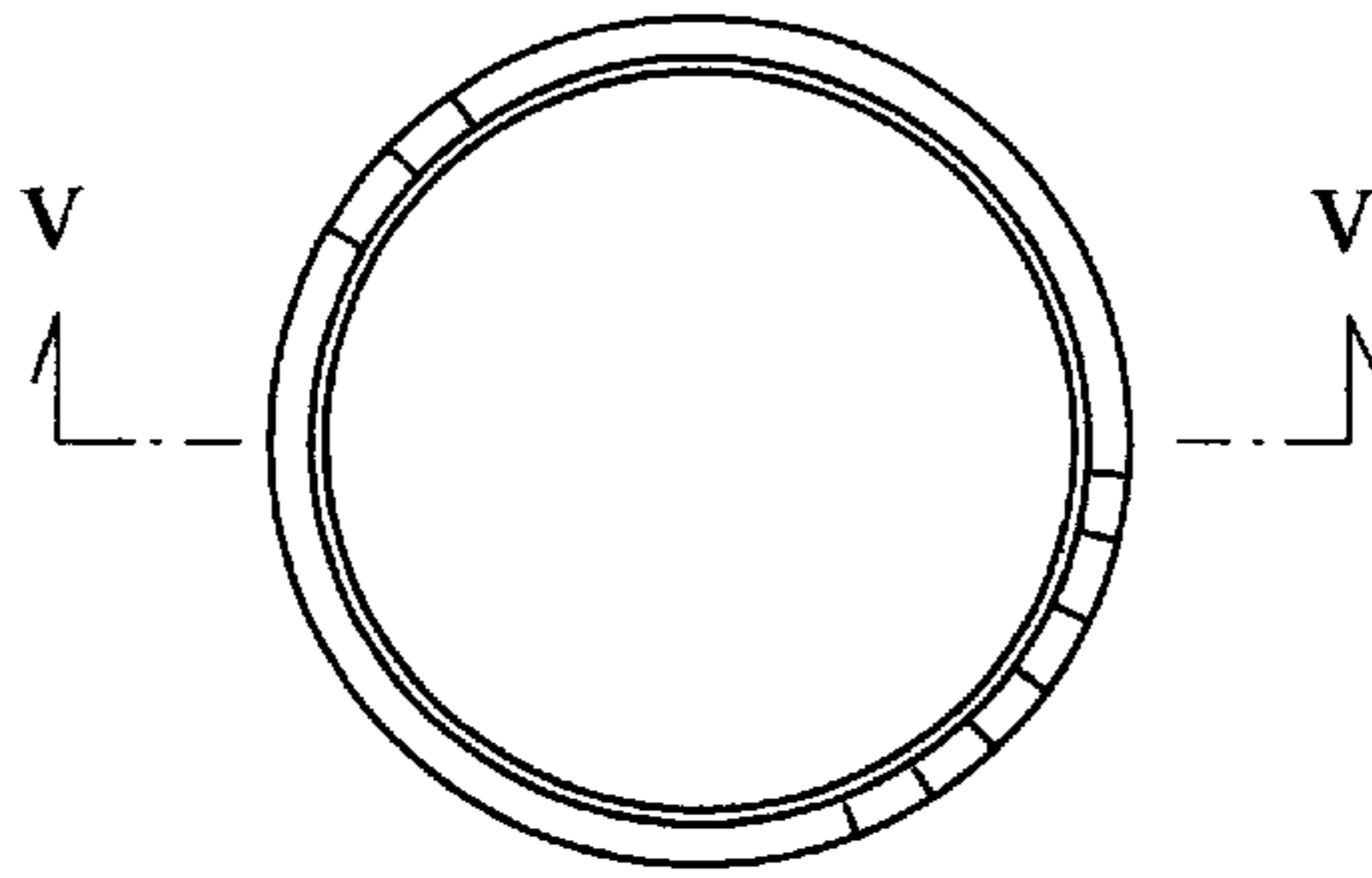


FIG. 4

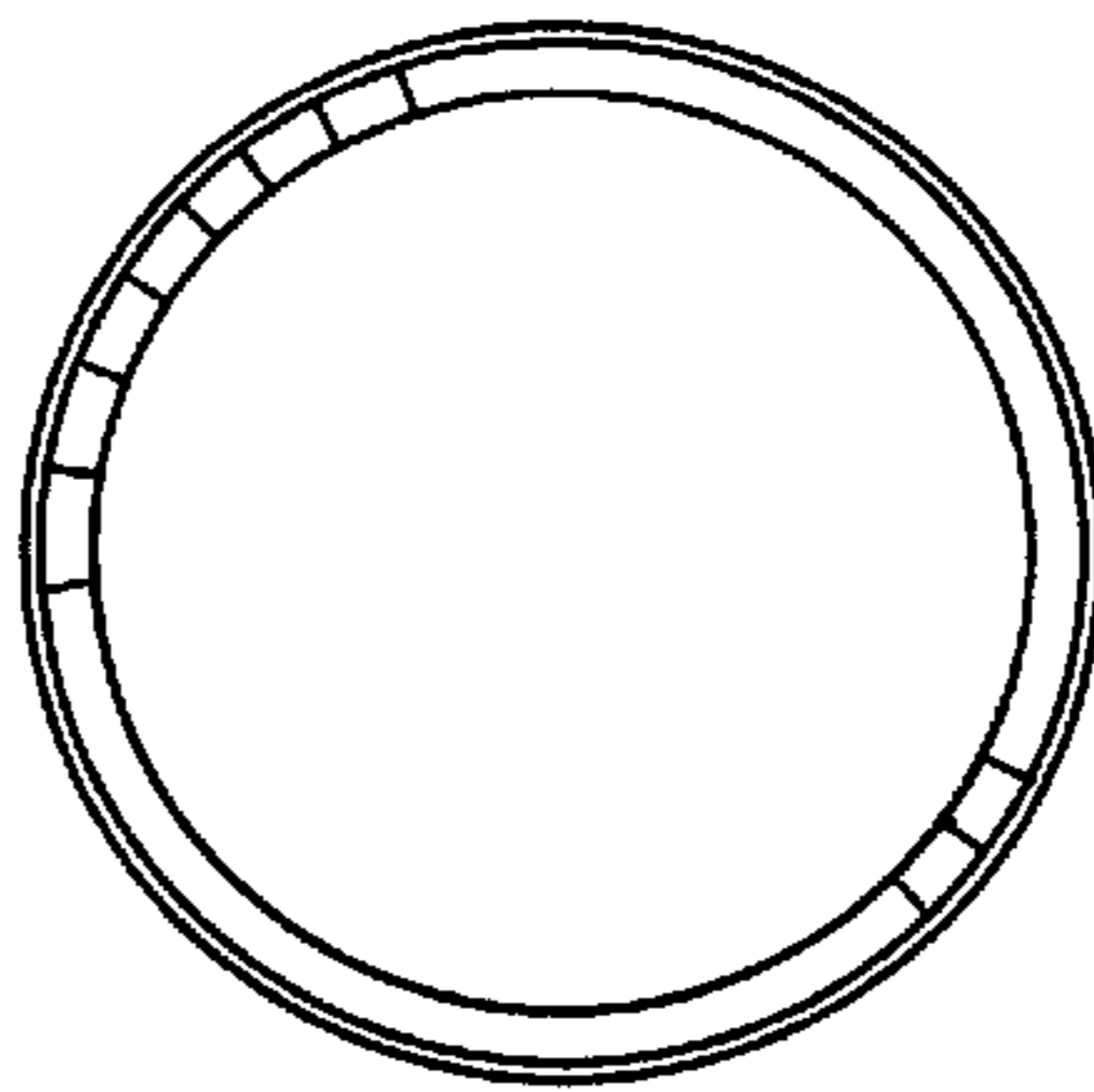


FIG. 5

